DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

	the original, first and sole inventes are listed below) of the subject				
REFLO	W SOLDERING APPARATUS				
the specificat	ion of which is attached hereto ur	nless the following is ch	ecked		
was filed	on MAY 1, 2003 as United State	es Application Number	or PCT International		
Applicatio	on Number <u>PCT/JP03/05589</u> and	was amended on	(if applicable).		
-	that I have reviewed and underst mended by any amendment refen		above-identified specification	, including the	
I acknowledge Regulations,	e the duty to disclose information § 1.56.	which is material to pa	tentability as defined in Title	37, Code of Federal	
for patent or i	n foreign priority benefits under inventor's certificate listed below tificate having a filing date befor	and have also identified	d below any foreign application	on for patent or	
		e that of the application	for which priority is claimed.	Priority Claimed	
(List prior foreig		T	16150000		
note A)	2002-141237 (Number)	Japan (Country)	16/5/2002 (Dav/Month/Year Filed)	☑ Yes ☐ No	
	2002 200540	_	,	5 1 y 1 y	
	2002-288548 (Number)	Japan (Country)	1/10/2002 (Day/Month/Year Filed)	⊠ Yes □ No	
,					
	2003-109942 (Number)	Japan	15/4/2003	Yes 🗌 No	
	(Number)	(Country)	(Day/Month/Year Filed)		
	2003-110130	Japan	15/4/2003	Yes □ No	
(C . D)	(Number)	(Country)	(Day/Month/Year Filed)		
(See note B)	- See attached list for	additional prior foreigr	applications		
insofar as the in the manner information w	n the benefit under Title 35, Unit subject matter of each of the clair provided by the first paragraph which is material to patentability ween the filing date of the price	ms of this application is of Title 35, United Stat as defined in Title 37, (not disclosed in the prior Un es Code, § 112, I acknowledg Code of Federal Regulations,	ited States application ge the duty to disclose § 1.56 which became	
(List prior U.S.			Stat	Status	
Applications)	(Application Serial No.)	(Filing Date)	Patented Pend	ling Abandoned	
	(Application Social No.)	(Ciling Data)	Patented Pend	ling Abandoned	
	(Application Serial No.)	(Filing Date)			
	(Application Serial No.)	(Filing Date)	☐ Patented ☐ Pend	ling Abandoned	
	(Ppunion Donai 110.)	(1 11116 Date)			

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Ratent and Trademark Office connected therewith:

23850

Please direct all communications to the following address:

23850 PATENT TRADEMARK OFFICE

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, ' 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

See note C)	Full name of sole or first Inventor's signature	inventor (given name, family name)	D .	aru YOKOTA		
	Residence S.	AM (A) 1 / 1/2		oer 15, 2004		
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	Inventor's signature		Date			
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		or (given name, family name)				
	Inventor's signature		Date			
	Residence		Citizenship			
	Post Office Address					
	. —					
		ntor (given name, family name)				
	Inventor's signature		Date			
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		or (given name, family name)				
	Inventor's signature		Date			
	Residence		Citizenship			
	Post Office Address					

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